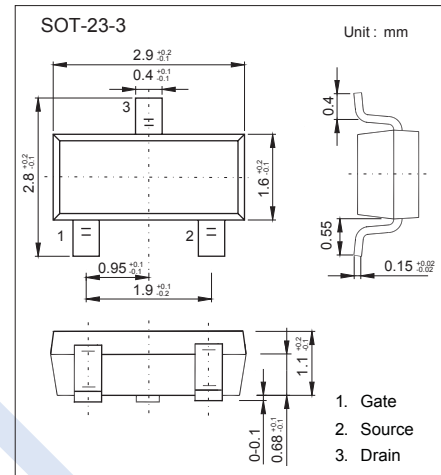


Depletion-Mode Power MOSFET

2KK5066

■ Features

- $BV_{DSX} = 150\text{ V}$
- $I_{DSS} = 200\text{ mA}$
- $R_{DS(ON)} < 15\ \Omega$
- High-threshold voltage, its typical value as high as -6V
- ESD improved Capability
- Depletion Mode (Normally On)
- Proprietary Advanced Planar Technology
- Rugged Polysilicon Gate Cell Structure
- Fast Switching Speed

■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSX}	150	V
Drain-Gate Voltage	V_{DGX}	150	
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	I_D	0.2	A
Pulsed Drain Current (Note 1)	I_{DM}	0.6	
Power Dissipation	P_D	0.5	W
Thermal Resistance, Junction- to-Ambient	$R_{\theta JA}$	250	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 to 150	

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

Depletion-Mode Power MOSFET

2KK5066

■ Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF Characteristics						
Drain-Source Breakdown Voltage	BV_{DSX}	$I_D = 250\ \mu\text{A}$, $V_{GS} = -15\text{V}$	150			V
Drain-to-Source Leakage Current	$I_{D(OFF)}$	$V_{DS} = 150\text{V}$, $V_{GS} = -15\text{V}$			10	μA
		$V_{DS} = 150\text{V}$, $V_{GS} = -15\text{V}$, $T_J = 125^\circ\text{C}$			1	mA
Gate to Source Leakage Current	I_{GSS}	$V_{DS} = 0\text{V}$, $V_{GS} = \pm 20\text{V}$			± 20	μA
ON Characteristics						
Saturated Drain-to-Source Current	I_{DSS}	$V_{DS} = 25\text{V}$, $V_{GS} = 0\text{V}$	200			mA
Gate-to-Source Cut-off Voltage	$V_{GS(OFF)}$	$V_{DS} = 3\text{V}$, $I_D = 8\ \mu\text{A}$	-7		-5	V
Static Drain-Source On-Resistance *	$R_{DS(ON)}$	$V_{GS} = 0\text{V}$, $I_D = 200\text{mA}$		10	15	Ω
Forward Transconductance	g_{FS}	$V_{DS} = 10\text{V}$, $I_D = 100\text{mA}$		0.24		S
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{GS} = 10\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$		12.8		pF
Output Capacitance	C_{oss}			5.4		
Reverse Transfer Capacitance	C_{rss}			3.3		
Total Gate Charge	Q_g	$V_{GS} = -10\text{V}\sim 0\text{V}$, $V_{DS} = 75\text{V}$, $I_D = 200\text{mA}$		3		nC
Gate Source Charge	Q_{gs}			0.23		
Gate Drain Charge	Q_{gd}			1.1		
Resistive Switching Characteristics						
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 75\text{V}$, $I_D = 200\text{mA}$, $R_G = 20\Omega$, $V_{GS} = -10\text{V}\sim 0\text{V}$,		7		ns
Turn-On Rise Time	t_r			16		
Turn-Off Delay Time	$t_{d(off)}$			25		
Turn-Off Fall Time	t_f			120		
Source-Drain Diode Characteristics						
Diode Forward Voltage	V_{SD}	$I_{SD} = 200\text{mA}$, $V_{GS} = -15\text{V}$			1.2	V

* : Pulse width $\leq 380\mu\text{s}$; duty cycle $\leq 2\%$.

■ Marking

Marking	KBR
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Depletion-Mode Power MOSFET

2KK5066

■ Typical Electrical Characteristics

Figure 1. Maximum Power Dissipation vs. Case Temperature

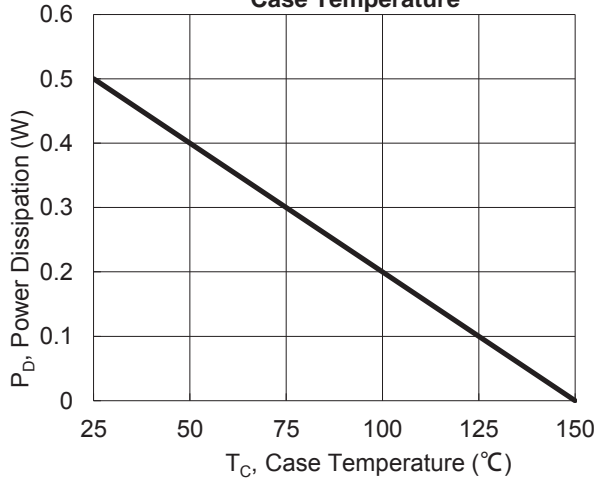


Figure 2. Maximum Continuous Drain Current vs Case Temperature

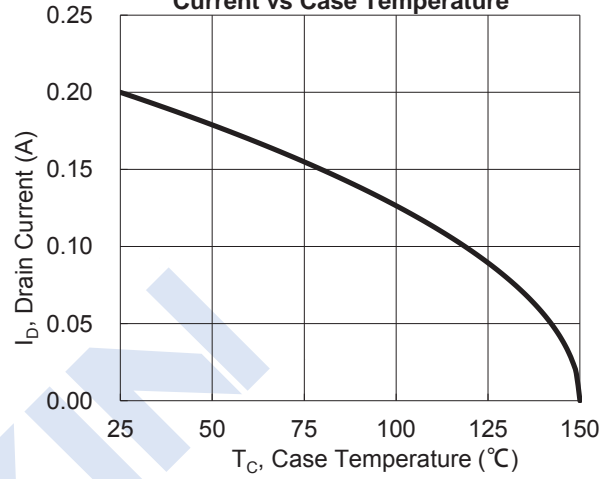


Figure 3. Typical Output Characteristics

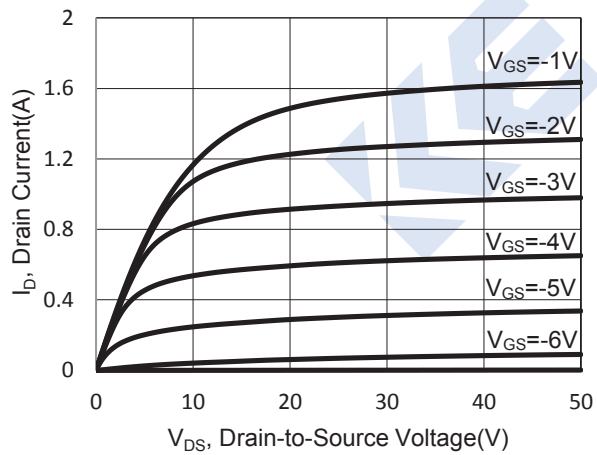


Figure 4. Typical Transfer Characteristics

